



- ⦿ AEC-Q200 Compliant
- ⦿ Designed for use with ADI LTC6804/681X series, NXP MC33771/33772 and TI BQ79616
- ⦿ Design Construction: Basic insulation per IEC 60664-1
- ⦿ Creepage Distance: $\geq 15\text{mm}$, per pollution 2 & material group 1
- ⦿ Operating Temperature: -40°C to $+125^{\circ}\text{C}$
- ⦿ Storage Temperature: -55°C to $+125^{\circ}\text{C}$
- ⦿ Lead Finish: Sn100
- ⦿ Moisture Sensitivity Level: 1

Electrical Specifications @ 25°C

Part Number	Turns Ratio ($\pm 5\%$)	Inductance 100kHz, 0.1 Vrms (μH)		Insertion Loss (dB MAX)	Return Loss (dB MIN)	Dielectric Withstanding Voltage 60S MIN (VDC)
	$\frac{(1-3)}{(6-4)}$	MIN	MAX	4 MHz	4 MHz	(1-3) to (6-4)
RA1063NL	1CT:1CT	150	450	1.2	6	7640

NOTES:

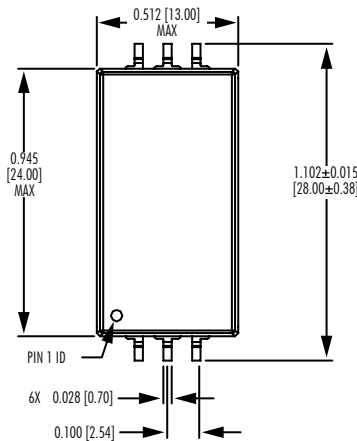
- For Tape & Reel packaging, add "T" suffix at the end of the part number: i.e. RA1063NLT

Mechanicals

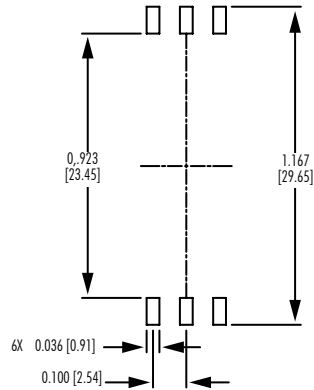
Electrical Schematics

RA1063NL

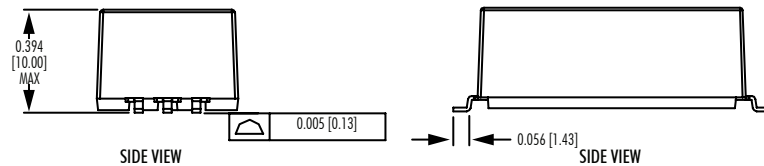
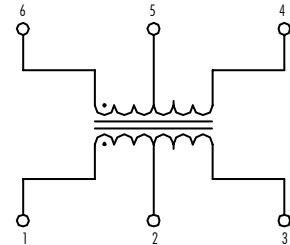
Dimensions: inch [mm]
Tolerance (unless otherwise specified): ± 0.010 [0.25]



TOP VIEW



SUGGESTED PAD LAYOUT
(REFERENCE ONLY)

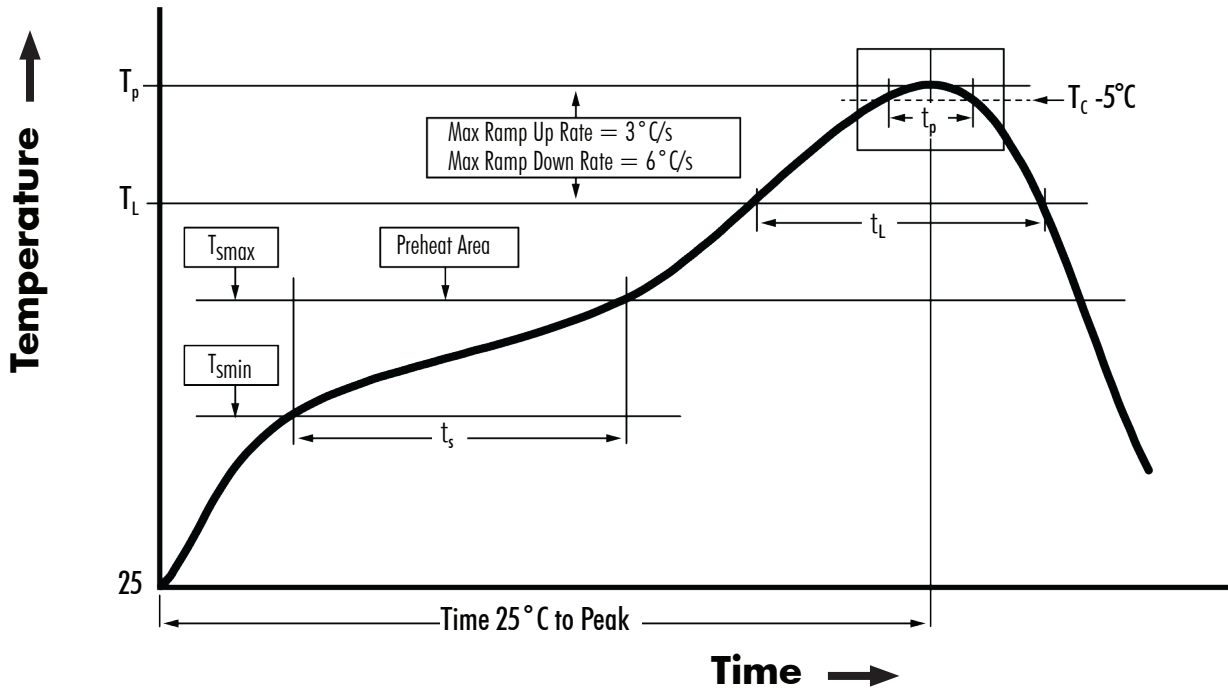


SIDE VIEW

SIDE VIEW



Non-Lead Recommended Reflow Profile (Based on J-STD-020D)



T_{SMIN} (°C)	T_{SMAX} (°C)	T_L (°C)	T_P (°C MAX)	t_s (s)	t_L (s)	t_p (s MAX)	Ramp-up rate (T_L to T_p)	Ramp-down rate (T_p to T_L)	Time 25°C to peak temperature (s MAX)
150	200	217	245	60 - 120	60 - 150	30	3°C/s MAX	6°C/s MAX	480

NOTES:

1. All temperatures measured on the package leads.
2. Maximum number of reflow cycles not to exceed 2.

